

Product / Package Information

Package	TSSOP
Body Size (mm)	4.4
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	2.94E-02	87.7	877000	49.97		499732
Thermosets	Phenol Resin	Proprietary	1.34E-03	4.0	40000	2.28		22793
Thermosets	Epoxy Resin 1	Proprietary	1.01E-03	3.0	30000	1.71		17095
Thermosets	Epoxy Resin 2	Proprietary	1.17E-03	3.5	35000	1.99		19944
Others	Others	Proprietary	5.03E-04	1.5	15000	0.85		8547
Other inorganic materials	Carbon Black	1333-86-4	1.01E-04	0.3	3000	0.17		1709
Subtotal			3.36E-02	100.00	1000000	56.98		569819

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.83 E-02	96.20	962000	30.99		309883
Copper & its alloys	Nickel	7440-02-0	5.69 E-04	3.00	30000	0.97		9664
Copper & its alloys	Silicon	7440-21-3	1.23 E-04	0.65	6500	0.21		2094
Copper & its alloys	Magnesium	7439-95-4	2.85 E-05	0.15	1500	0.05		483
Subtotal			1.90 E-02	100.00	1000000	32.21		322123

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.90 E-04	100.0	1000000	0.32		3221

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.26 E-03	100.0	1000000	2.14		21423

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	5.54 E-04	99.00	407647	0.94		9399
Precious metals	Palladium	7440-05-3	5.59 E-06	1.00	4118	0.01		95
Subtotal			5.59 E-04	100.0	1000000	0.95		9494

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	3.00 E-03	100.0	1000000	5.09		50862

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.05 E-03	77.00	770000	1.78		17754
Other organic materials	Acrylic resin	Proprietary	9.51 E-05	7.00	70000	0.16		1614
Other organic materials	Acrylate	Proprietary	7.47 E-05	5.50	55000	0.13		1268
Other organic materials	Polybutadiene derivative	Proprietary	6.11 E-05	4.50	45000	0.10		1038
Thermoset	Epoxy resin	Proprietary	3.40 E-05	2.50	25000	0.06		576
Other organic materials	Butadiene Copolymer	Proprietary	2.04 E-05	1.50	15000	0.03		346
Others	Additive	Proprietary	2.04 E-05	1.50	15000	0.03		346
Others	Peroxide	Proprietary	6.79 E-06	0.50	5000	0.012		115
Subtotal			1.36 E-03	100.0	1000000	2.31		23057

Package Totals			Weight (g) 5.89 E-02			Percentage (%) 100		PPM 1000000
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Control ID: MS012252APKG4239

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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